



Sym	Nº	Mils	MM	Qty	Plated
+	1	8	0.20	165	YES
x	2	20	0.51	1	YES
▣	3	35	0.89	3	NOT
◊	4	116	2.95	4	NOT

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. FABRICATE TO MEET OR EXCEED THE REQUIREMENTS OF IPC 6011/6012 CLASS 2, AS DEFINED IN IPC-2221
- 2. PREPREG MATERIAL: MATERIAL WITH TG > 170
- 3. MINIMUM TRACE WIDTH IS .006, MINIMUM SPACING IS .006
- 4. BOARD FINISH: ELECTROLESS NICKEL, IMMERSION GOLD (ENIG).
- 5. FLAMMABILITY: MATERIALS TO MEET UL94V-0 SPECIFICATION.
- 6. APPLY LPI SOLDERMASK (BLUE) ON BOTH SIDES.
- 7. SILKSCREEN ON BOTH SIDES USING WHITE EPOXY INK, REGISTRATION TO BE .01. CLEAR SILKSCREEN FROM ALL EXPOSED PADS.
- 8. THE FABRICATED BOARD SHALL BE RoHS COMPLIANT.

4 LAYER PCB STACKUP, ~0.062" finished thickness

Layer 1	Top Copper 1 oz, 1.35mil 1x7628, 2x1080, 0.0119inch
Layer 2	Inner Copper 1 oz, 1.35mil Inner layer core, 0.028inch
Layer 3	Inner Copper 1 oz, 1.35mil 1x7628, 2x1080, 0.0119inch
Layer 4	Bottom Copper 1 oz, 1.35mil

Rigado, LLC

TITLE: BMD-200\_eval

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